



**RF360
Europe GmbH**

Data sheet

SAW duplexer

Small cell & femtocell
LTE band 5

Series/type: B8013

Ordering code: B39881B8013P810

Date: December 11, 2018

Version: 2.9

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A Qualcomm – TDK Joint Venture

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Please read **Cautions and warnings** and
Important notes at the end of this document.

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1 Application

- Low-loss SAW duplexer for LTE small cell systems (Band 5)
- Usable pass band 25MHz
- RX=uplink=824-849MHz
- TX=downlink=869-894MHz

2 Features

- Industrial grade qualified family
- Package size 2.5 ± 0.1 mm \times 2.0 ± 0.1 mm
- Package height 0.5 mm (max.)
- Approximate weight 0.01 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

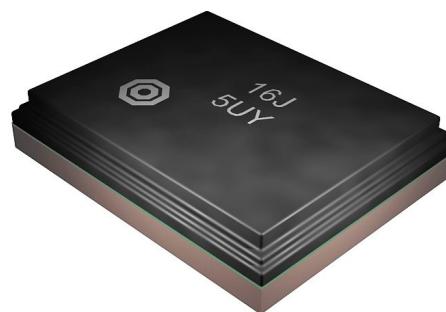
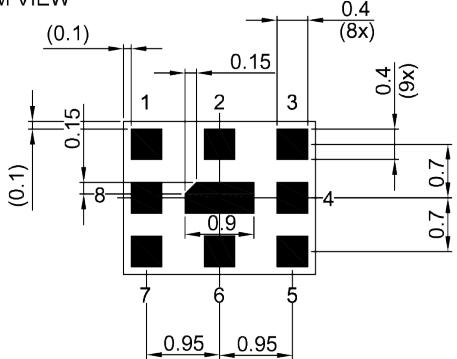


Figure 1: Picture of component with example of product marking.

3 Package

BOTTOM VIEW

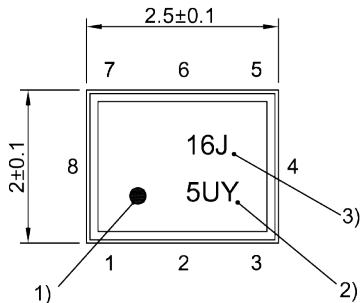


Pad and pitch tolerance ± 0.05

SIDE VIEW

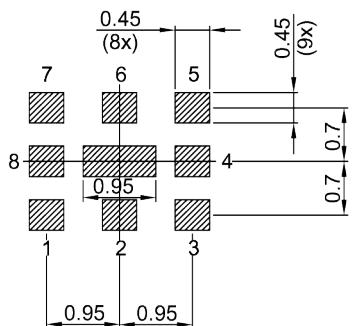


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.5 mm (max.). See Sec. Package information (p. 26).

5 Matching circuit

■ $L_{p6} = 8.7 \text{ nH}$

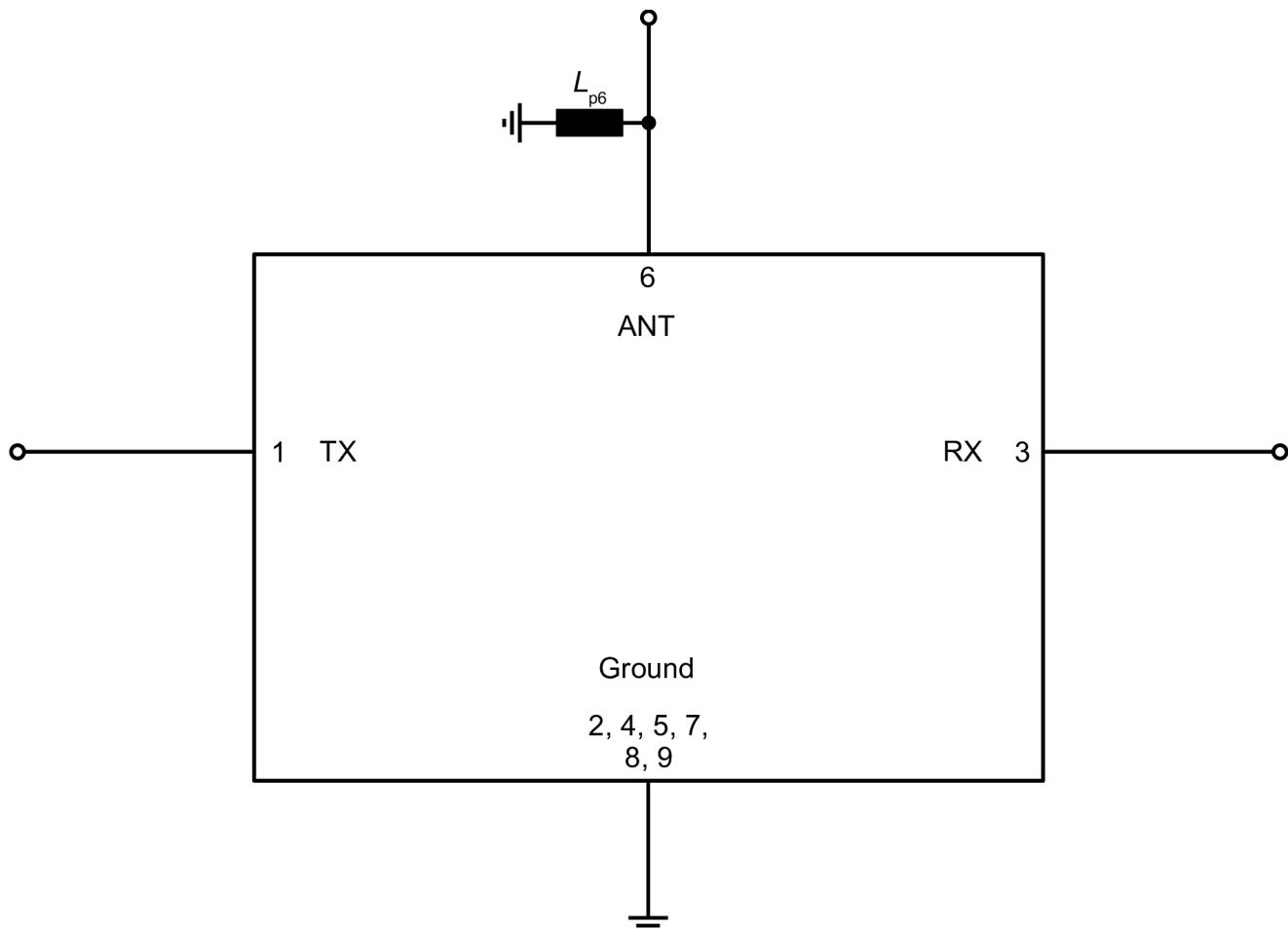


Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= $-10^{\circ}\text{C} \dots +85^{\circ}\text{C}$
TX terminating impedance	Z_{TX}	= $50\ \Omega$
ANT terminating impedance	Z_{ANT}	= $50\ \Omega$ with par. $8.7\ \text{nH}^1)$
RX terminating impedance	Z_{RX}	= $50\ \Omega$

Characteristics TX – ANT			min. for T_{SPEC}	typ. @ $+25^{\circ}\text{C}$	max. for T_{SPEC}	
Center frequency	f_{C}	—	881.5	—	MHz	
Average insertion attenuation	$\alpha_{\text{INT,avg}}^2)$					
869 ... 874	MHz	—	1.9	2.5	dB	
874 ... 889	MHz	—	1.5	2.5	dB	
889 ... 894	MHz	—	1.7	2.5	dB	
Maximum insertion attenuation	α_{max}					
869 ... 894	MHz	—	1.9	2.5 ³⁾	dB	
Amplitude ripple (p-p)	$\Delta\alpha$					
869 ... 894	MHz	—	0.6	1.3 ⁴⁾	dB	
Maximum VSWR	VSWR_{max}					
@ TX port	869 ... 894	MHz	—	1.9	2.1 ⁵⁾	
@ ANT port	869 ... 894	MHz	—	1.8	2.1 ⁵⁾	
Maximum error vector magnitude	$\text{EVM}_{\text{max}}^6)$					
871.4 ... 891.6	MHz	—	1.4	3.5	%	
Minimum attenuation	α_{min}					
824 ... 849	MHz	52	59	—	dB	
1574.4 ... 1576.4	MHz	45	58	—	dB	
1602.5 ... 1615.5	MHz	35	59	—	dB	
1710 ... 1788	MHz	40	59	—	dB	
1850 ... 1910	MHz	40	57	—	dB	
1920 ... 1980	MHz	40	55	—	dB	
2400 ... 2484	MHz	40	50	—	dB	
2607 ... 2682	MHz	37	47	—	dB	
3476 ... 3576	MHz	35	49	—	dB	

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Specification for ILmax is 2.6dB for $-20^{\circ}\text{C} \dots +85^{\circ}\text{C}$.

⁴⁾ Specification for AR is 1.4dB for $-20^{\circ}\text{C} \dots +85^{\circ}\text{C}$.

⁵⁾ Specification for VSWR is 2.2 for $-20^{\circ}\text{C} \dots +85^{\circ}\text{C}$.

⁶⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	T_{SPEC}	= $-40^{\circ}\text{C} \dots +95^{\circ}\text{C}$
TX terminating impedance	Z_{TX}	= $50\ \Omega$
ANT terminating impedance	Z_{ANT}	= $50\ \Omega$ with par. $8.7\ \text{nH}^1$
RX terminating impedance	Z_{RX}	= $50\ \Omega$

Characteristics TX – ANT			min. for T_{SPEC}	typ. @ $+25^{\circ}\text{C}$	max. for T_{SPEC}	
Center frequency		f_c	—	881.5	—	MHz
Average insertion attenuation		$\alpha_{\text{INT,avg}}^2)$				
	869 ... 874	MHz	—	1.9	3.0	dB
	874 ... 889	MHz	—	1.5	3.0	dB
	889 ... 894	MHz	—	1.7	3.0	dB
Maximum insertion attenuation		α_{max}				
	869 ... 894	MHz	—	1.9	3.0	dB
Amplitude ripple (p-p)		$\Delta\alpha$				
	869 ... 894	MHz	—	0.6	1.7	dB
Maximum VSWR		VSWR_{max}				
@ TX port	869 ... 894	MHz	—	1.9	2.3	
@ ANT port	869 ... 894	MHz	—	1.8	2.3	
Maximum error vector magnitude		$\text{EVM}_{\text{max}}^3)$				
	871.4 ... 891.6	MHz	—	1.4	4.0	%
Minimum attenuation		α_{min}				
	824 ... 849	MHz	52	59	—	dB
	1574.4 ... 1576.4	MHz	45	58	—	dB
	1602.5 ... 1615.5	MHz	35	59	—	dB
	1710 ... 1788	MHz	40	59	—	dB
	1850 ... 1910	MHz	40	57	—	dB
	1920 ... 1980	MHz	40	55	—	dB
	2400 ... 2484	MHz	40	50	—	dB
	2607 ... 2682	MHz	37	47	—	dB
	3476 ... 3576	MHz	35	49	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 8.7 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency	f_c	—	836.5	—	MHz	
Average insertion attenuation	$\alpha_{\text{INT,avg}}^{2)}$					
824 ... 829	MHz	—	2.1	3.1	dB	
829 ... 844	MHz	—	1.8	3.1	dB	
844 ... 849	MHz	—	1.7	3.1	dB	
Maximum insertion attenuation	α_{max}					
824 ... 849	MHz	—	2.6	3.1 ³⁾	dB	
Amplitude ripple (p-p)	$\Delta\alpha$					
824 ... 849	MHz	—	1.3	1.8 ⁴⁾	dB	
Maximum VSWR	VSWR_{max}					
@ ANT port	824 ... 849	MHz	—	1.9	2.3 ⁵⁾	
@ RX port	824 ... 849	MHz	—	2.0	2.3 ⁵⁾	
Maximum error vector magnitude	$\text{EVM}_{\text{max}}^{6)}$					
826.4 ... 846.6	MHz	—	3.0	4.5	%	
Minimum attenuation	α_{min}					
869 ... 894	MHz	50	57	—	dB	
1648 ... 1698	MHz	45	51	—	dB	
1840 ... 1870	MHz	40	48	—	dB	
1930 ... 1990	MHz	40	46	—	dB	
2110 ... 2170	MHz	35	45	—	dB	
2400 ... 2484	MHz	35	42	—	dB	
2472 ... 2547	MHz	35	41	—	dB	
3296 ... 3396	MHz	32	39	—	dB	

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Specification for ILmax is 3.2dB for -20 °C ... +85 °C.

⁴⁾ Specification for AR is 1.9dB for -20 °C ... +85 °C.

⁵⁾ Specification for VSWR is 2.4 for -20 °C ... +85 °C.

⁶⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 8.7 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency	f_c	—	836.5	—	MHz	
Average insertion attenuation	$\alpha_{\text{INT,avg}}$ ²⁾					
824 ... 829	MHz	—	2.1	3.8	dB	
829 ... 844	MHz	—	1.8	3.8	dB	
844 ... 849	MHz	—	1.7	3.8	dB	
Maximum insertion attenuation	α_{max}					
824 ... 849	MHz	—	2.6	3.8	dB	
Amplitude ripple (p-p)	$\Delta\alpha$					
824 ... 849	MHz	—	1.3	2.5	dB	
Maximum VSWR	VSWR_{max}					
@ ANT port	824 ... 849	MHz	—	1.9	2.5	
@ RX port	824 ... 849	MHz	—	2.0	2.5	
Maximum error vector magnitude	EVM_{max} ³⁾					
826.4 ... 846.6	MHz	—	3.0	5.0	%	
Minimum attenuation	α_{min}					
869 ... 894	MHz	50	55	—	dB	
1648 ... 1698	MHz	45	51	—	dB	
1840 ... 1870	MHz	40	48	—	dB	
1930 ... 1990	MHz	40	46	—	dB	
2110 ... 2170	MHz	35	45	—	dB	
2400 ... 2484	MHz	35	42	—	dB	
2472 ... 2547	MHz	35	41	—	dB	
3296 ... 3396	MHz	32	39	—	dB	

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 8.7 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX		min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Average isolation	$\alpha_{\text{INT,avg}}$ ²⁾				
	824 ... 849 MHz	52	58	—	dB
	869 ... 894 MHz	53	61	—	dB
Minimum isolation	α_{min}				
	824 ... 849 MHz	52	58	—	dB
	869 ... 894 MHz	53	56	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

Temperature range for specification

T_{SPEC} = $-40^{\circ}\text{C} \dots +95^{\circ}\text{C}$

TX terminating impedance

Z_{TX} = $50\ \Omega$

ANT terminating impedance

Z_{ANT} = $50\ \Omega$ with par. $8.7\ \text{nH}^1$

RX terminating impedance

Z_{RX} = $50\ \Omega$

Characteristics TX – RX

			min. for T_{SPEC}	typ. @ $+25^{\circ}\text{C}$	max. for T_{SPEC}	
Average isolation		$\alpha_{\text{INT,avg}}^{2)}$				
	824 ... 849	MHz	52	58	—	dB
Minimum isolation		α_{min}				
	824 ... 849	MHz	52	56	—	dB
	869 ... 894	MHz	52	56	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

7 Maximum ratings

Operable temperature	$T_{OP} = -40 \text{ }^{\circ}\text{C} \dots +95 \text{ }^{\circ}\text{C}$	
Storage temperature	$T_{STG}^{1)} = -40 \text{ }^{\circ}\text{C} \dots +95 \text{ }^{\circ}\text{C}$	
DC voltage	$ V_{DC} ^{2)} = 0 \text{ V}$	
ESD voltage		
	$V_{ESD}^{3)} = 100 \text{ V}$	Machine model.
	$V_{ESD}^{4)} = 250 \text{ V}$	Human body model.
Input power	P_{IN}	
@ TX port: 871.5 ... 891.5 MHz	28 dBm ^{5), 6)}	5 MHz LTE downlink signal (25 RB) for 100000 h @ 55 °C. P_{IN} 28 dBm average - 39 dBm peak Source and load impedance 50 Ω.
@ TX port: other frequency ranges	10 dBm	Source and load impedance 50Ω.
Operating lifetime with output power at antenna 871.5 ... 891.5 MHz	$P_{OUT}^{7)} = 24 \text{ dBm}$	Continuous wave for 100000 h @ 55 °C. Source and load impedance 50Ω.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ Expected lifetime according to accelerated power durability tests, and wear out models.

⁶⁾ T_{SPEC} is the ambient temperature of the PCB at component position. Specified min./max values from section 6 "characteristics" for maximum input power 28dBm are valid for temperature up to 55°C.

⁷⁾ According to accelerated high temperature operating life (HTOL) test.

8 Transmission coefficients

8.1 TX – ANT

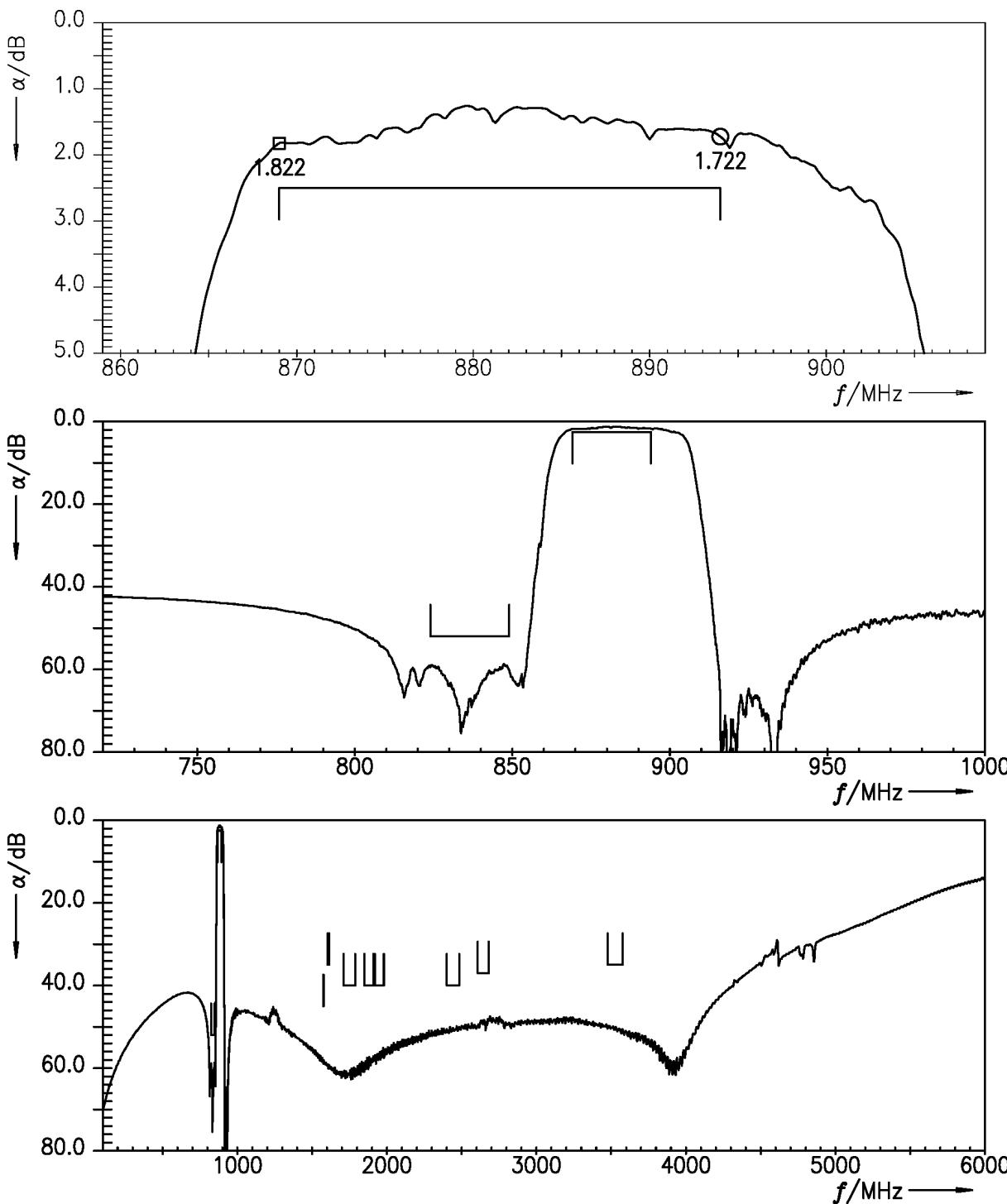


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

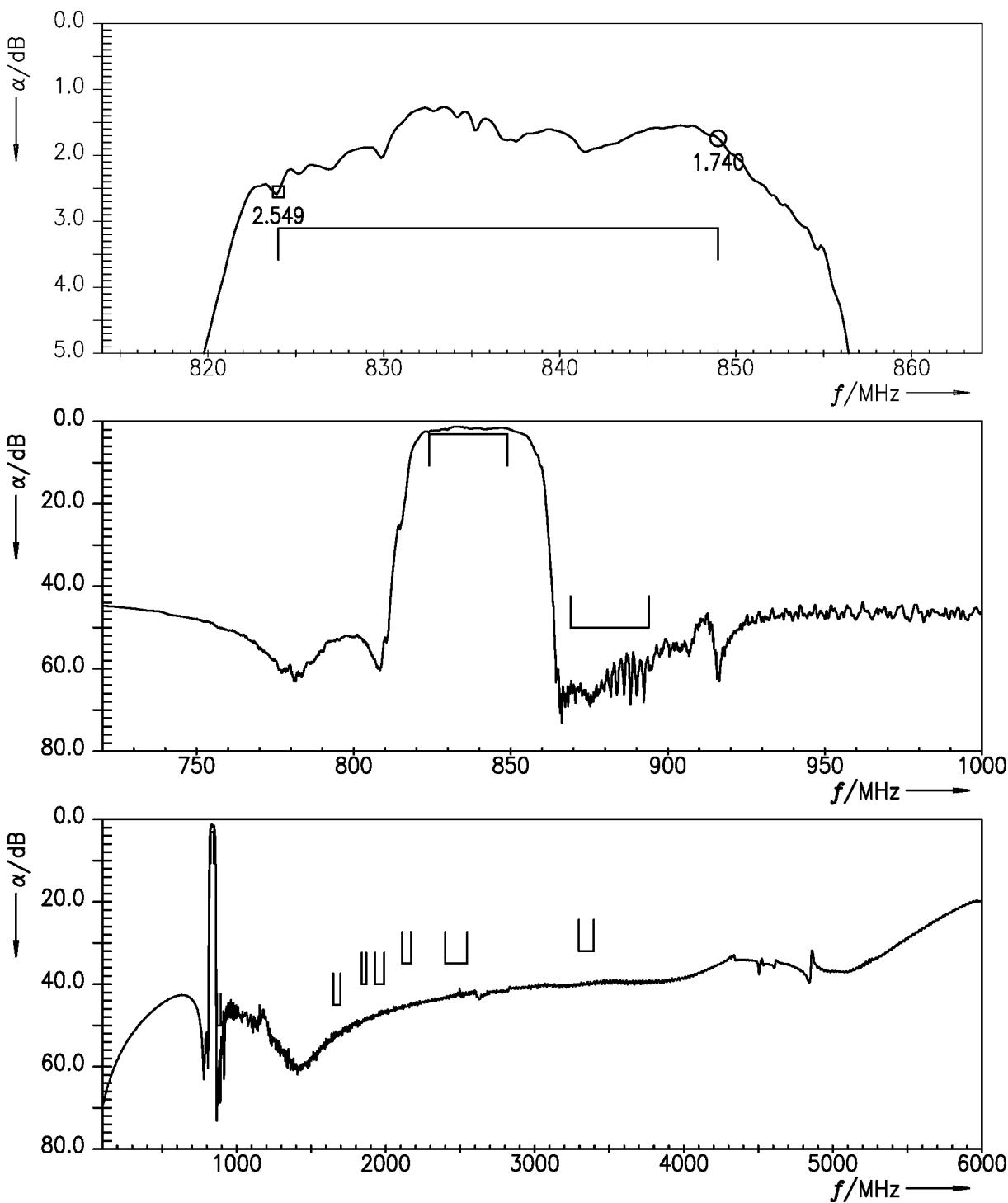


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

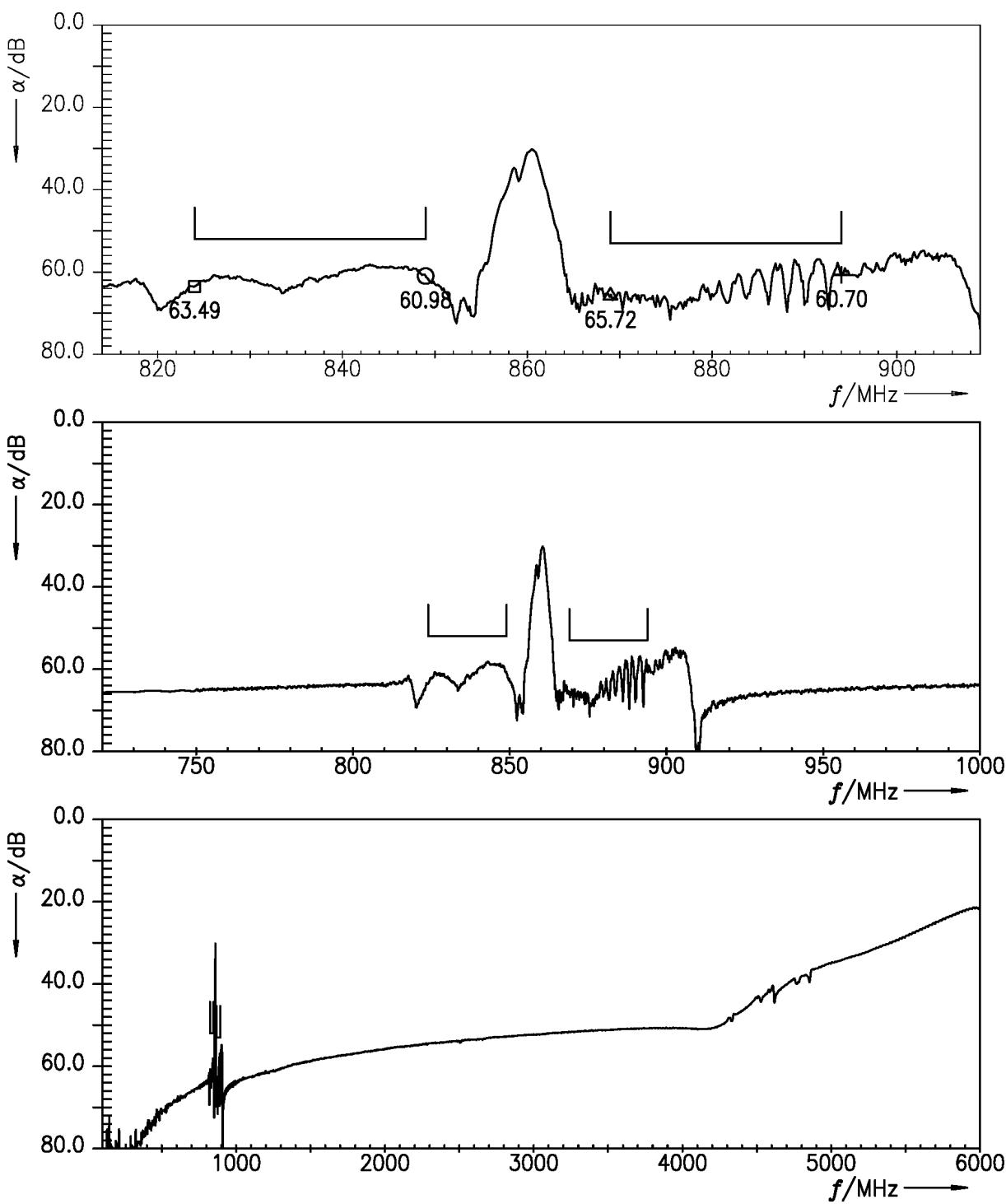


Figure 6: Isolation TX – RX.

9 Reflection coefficients

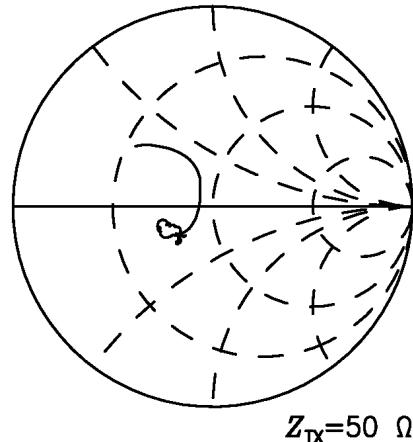
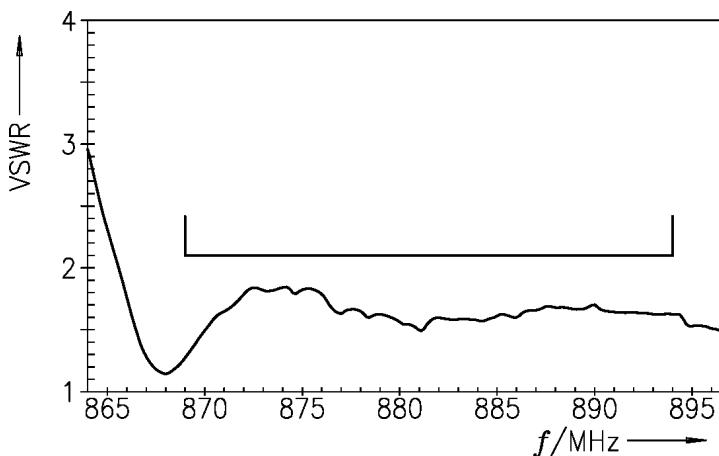


Figure 7: Reflection coefficient at TX port.

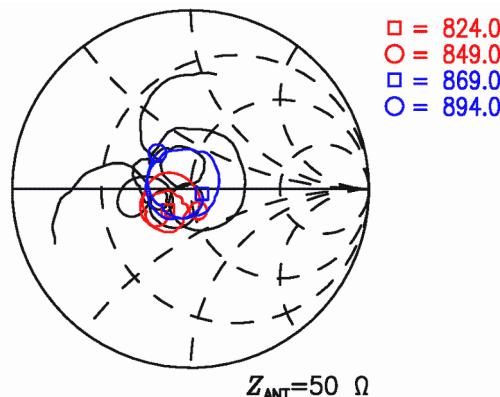
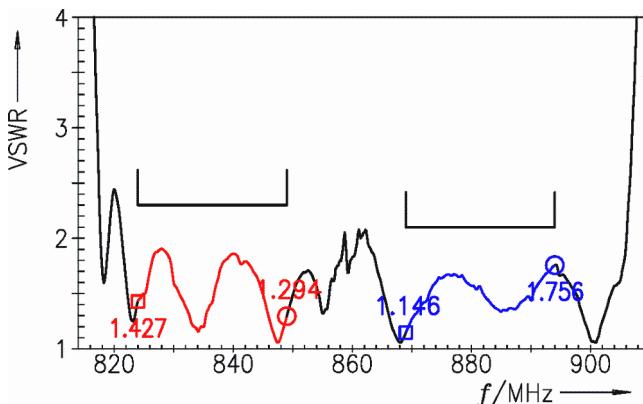


Figure 8: Reflection coefficient at ANT port.

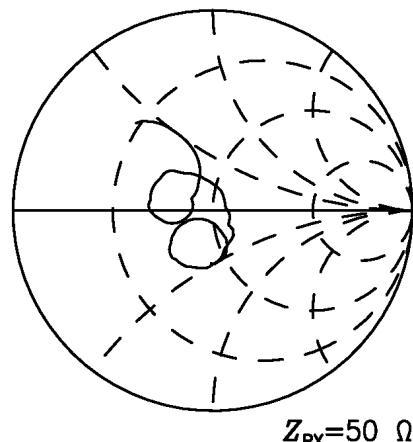
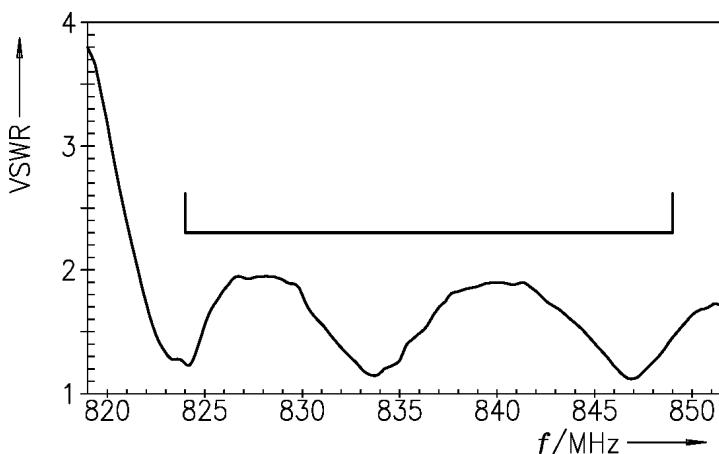
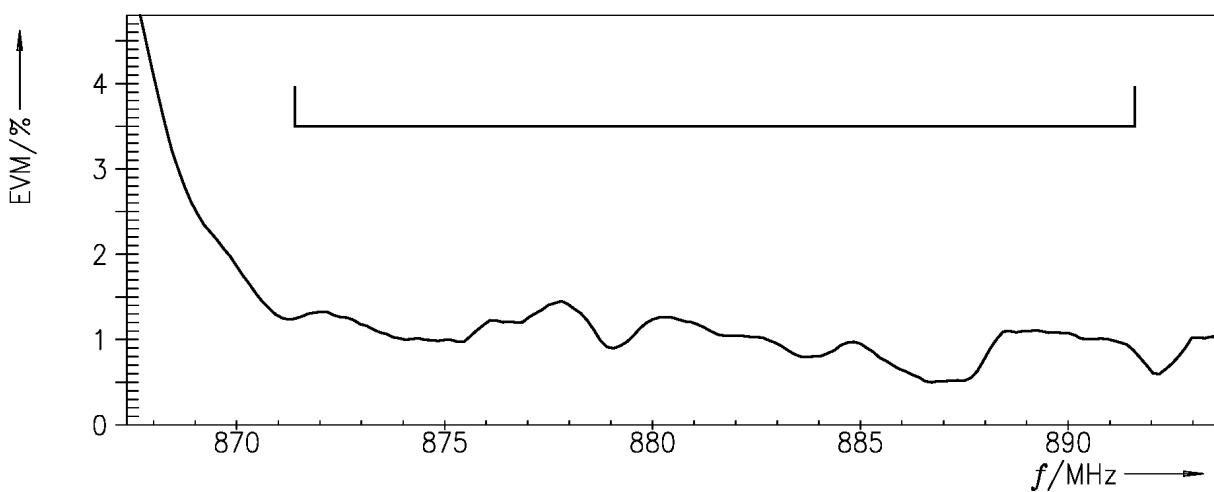
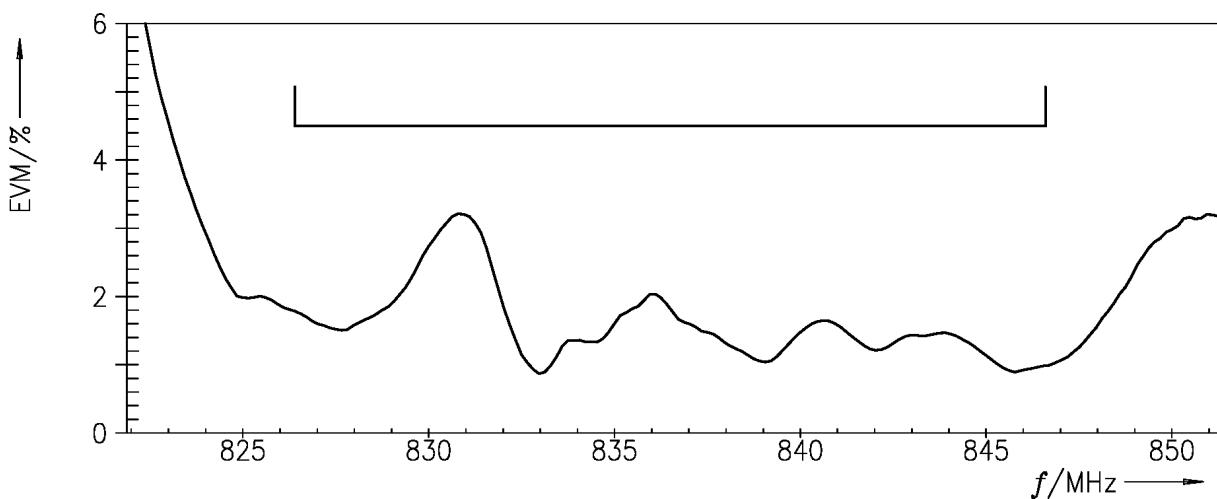


Figure 9: Reflection coefficient at RX port.

10 EVMs**10.1 TX – ANT****Figure 10:** Error vector magnitude TX – ANT.

10.2 ANT – RX**Figure 11:** Error vector magnitude ANT – RX.

11 Packing material

11.1 Tape

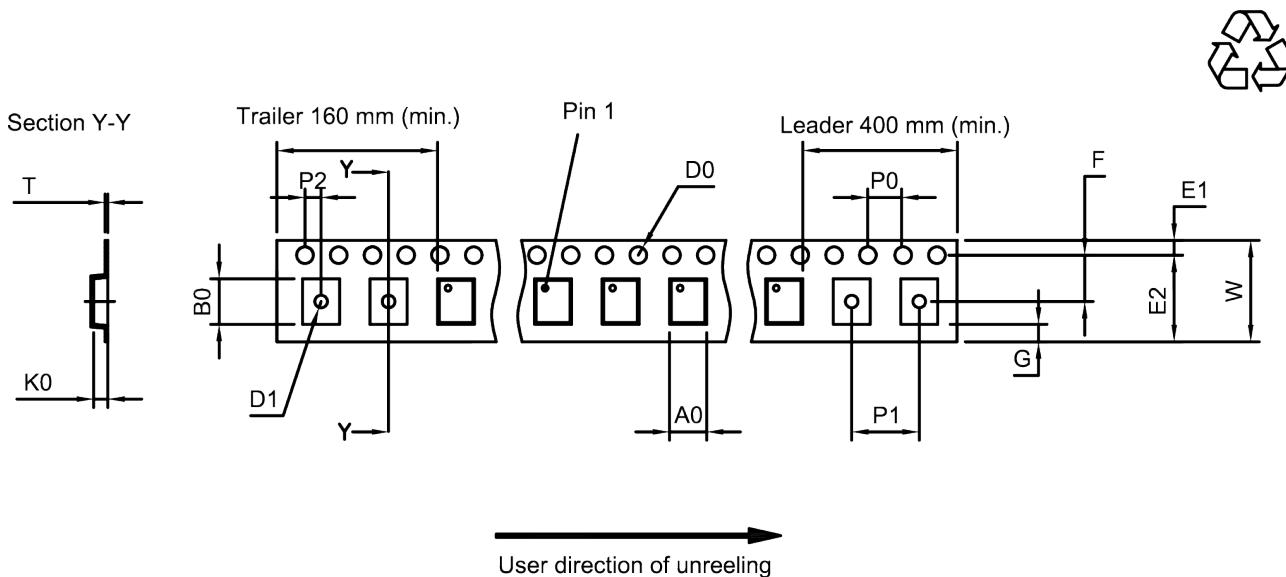


Figure 12: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	2.25 ± 0.05 mm	E_2	6.25 mm (min.)	P_1	4.0 ± 0.1 mm
B_0	2.75 ± 0.05 mm	F	3.5 ± 0.05 mm	P_2	2.0 ± 0.05 mm
D_0	$1.5 \pm 0.1/-0$ mm	G	0.75 mm (min.)	T	0.25 ± 0.03 mm
D_1	1.0 mm (min.)	K_0	0.6 ± 0.05 mm	W	$8.0 \pm 0.3/-0.1$ mm
E_1	1.75 ± 0.1 mm	P_0	4.0 ± 0.1 mm		

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

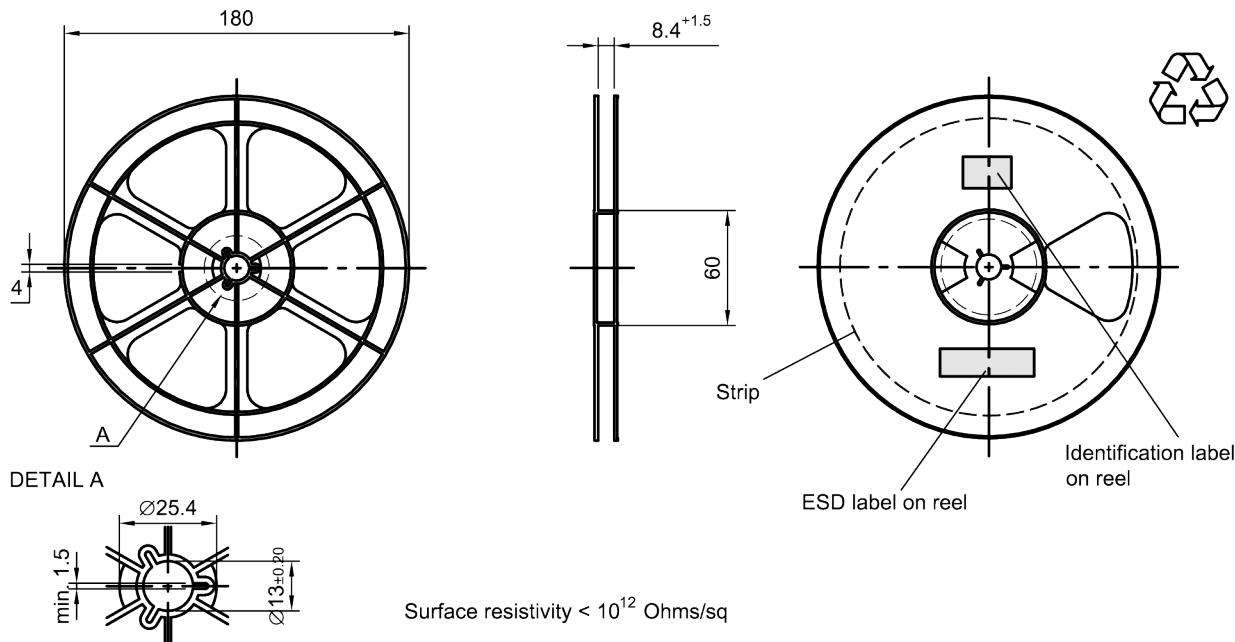


Figure 13: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

Printing
on vacumbag

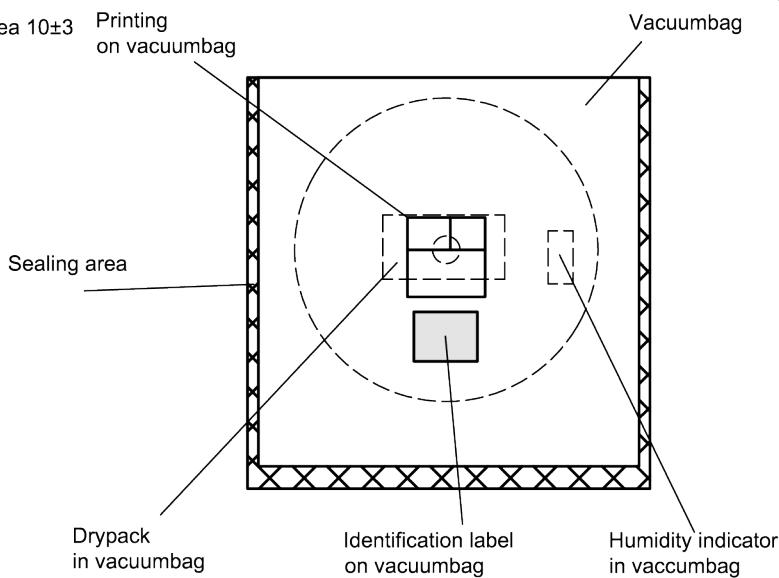


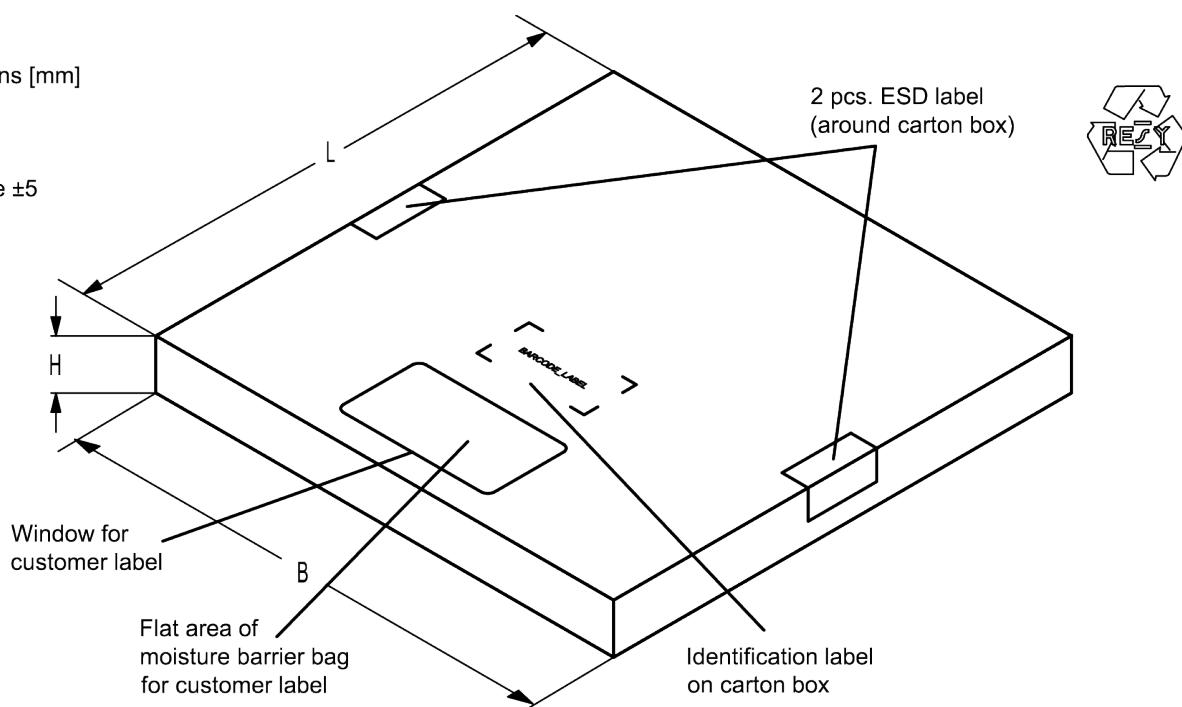
Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Dimensions [mm]

L = 188

B = 188

H = 30

Tolerance ± 5 **Figure 15:** Drawing of folding box for reel with diameter of 180 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code,
is encoded by a special BASE32 code into a 3 digit marking.

e.g., B3xxxxB**1234**xxxx,

Example of decoding type number marking on device in decimal code.

$$\begin{array}{lll} \mathbf{16J} & \Rightarrow & \mathbf{1234} \\ 1 \times 32^2 + 6 \times 32^1 + 18 \ (\mathbf{=J}) \times 32^0 & = & 1234 \end{array}$$

The BASE32 code for product type B8013 is 7TD.

■ Lot number:

The last 5 digits of the lot number,
are encoded based on a special BASE47 code into a 3 digit marking.

e.g., **12345**,

Example of decoding lot number marking on device in decimal code.

$$\begin{array}{lll} \mathbf{5UY} & \Rightarrow & \mathbf{12345} \\ 5 \times 47^2 + 27 \ (\mathbf{=U}) \times 47^1 + 31 \ (\mathbf{=Y}) \times 47^0 & = & 12345 \end{array}$$

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	$\leq 3 \text{ K/s}$
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220 \text{ }^{\circ}\text{C}$	30 s to 70 s
$T > 230 \text{ }^{\circ}\text{C}$	min. 10 s
$T > 245 \text{ }^{\circ}\text{C}$	max. 20 s
$T \geq 255 \text{ }^{\circ}\text{C}$	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	$\leq 3 \text{ K/s}$
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

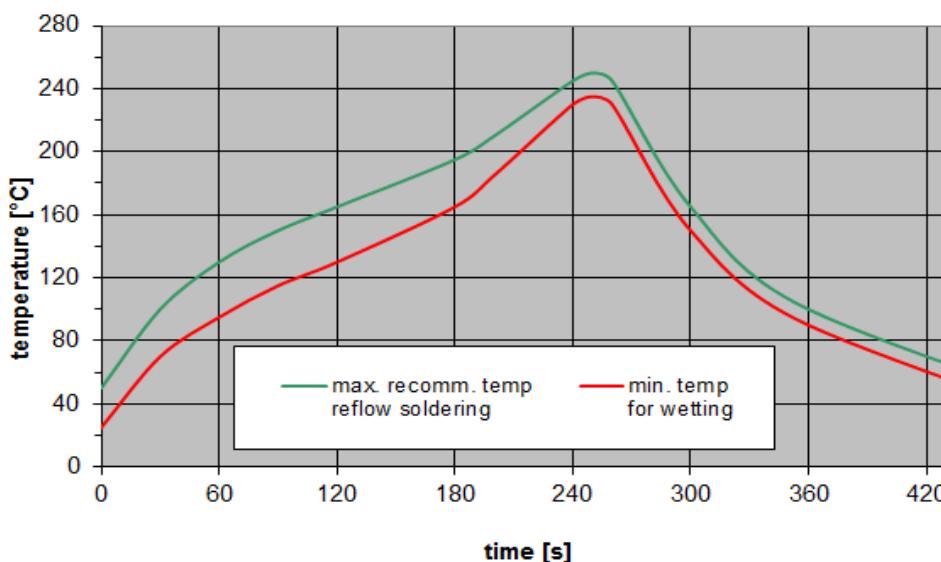


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B39881B8013P810	5000 pcs

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that **such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
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